

**IN THE CLAIMS**

1. (currently amended)      An apparatus comprising:
- a device chip including substrate and at least one circuit element fabricated on the substrate;
- a cap over said device chip, said cap including a gasket;
- bonding agent bonding said cap to said device chip defining a hermetically sealed cavity having an inner surface and an outer surface; and
- caulking agent at least partially surrounding said bonding agent reinforcing the hermetically seal, said caulking agent surrounding said bonding agent at least one of two surfaces of the gasket, the two surfaces being the inner surface and the outer surface.
- ~~a cap bonded to said device chip, said device chip and said cap defining a hermetically sealed cavity wherein the cavity is sealed with bonding agent and caulking agent.~~
2. (original)      The apparatus recited in claim 1 wherein the bonding agent comprises gold.
3. (original)      The apparatus recited in claim 1 wherein the caulking agent is selected from a group consisting of amorphous fluorocarbon polymer, polyimide materials, and benzocyclobutene (BCB) based materials.
4. (original)      The apparatus recited in claim 1 wherein the circuit element comprises a resonator.
5. (currently amended)      The apparatus recited in claim 1 wherein the caulking agent ~~caulks at least a portion of the bonding agent~~ further surrounds at least a portion of the gasket.
6. (currently amended)      The apparatus recited in claim 1 wherein the caulking agent

~~caulks~~ surrounds at least a portion of the cap.

7. (currently amended) The apparatus recited in claim 1 wherein said cap includes gasket having an inner surface and an outer surface and wherein the caulking agent ~~caulks~~ covers the inner surface of the gasket.
8. (currently amended) The apparatus recited in claim 1 wherein said cap includes gasket having an inner surface and an outer surface and wherein the caulking agent ~~caulks~~ covers the outer surface of the gasket.
9. (original) The apparatus recited in claim 1 comprising multiple layers of the caulking agent.
10. (original) The apparatus recited in claim 9 wherein the multiple layers of the caulking agent comprises layers having different caulking material relative to other layers of the caulking agent.
11. (original) The apparatus recited in claim 8 wherein the multiple layers of the caulking agent comprises layers having the same caulking material relative to other layers of the caulking agent.
12. (previously withdrawn) A method of manufacturing an apparatus, the method comprising:  
fabricating a device chip including a substrate and at least one circuit element on the substrate;  
fabricating a cap;  
bonding the cap on the device chip such that a sealed cavity is formed; and  
reflowing caulking agent further sealing the cavity.
13. (previously withdrawn) The method recited in claim 12 wherein the step of

fabricating the device chip includes a step of depositing caulking agent on the device chip.

14. (previously withdrawn) The method recited in claim 12 wherein the step of fabricating the cap includes a step of depositing caulking agent on the cap.
15. (previously withdrawn) The method recited in claim 12 wherein the cap is bonded to the device chip using bonding agent comprising gold.
16. (previously withdrawn) The method recited in claim 12 wherein the caulking agent is selected from a group consisting of amorphous fluorocarbon polymer, polyimide materials, and benzocyclobutene (BCB) based materials.
17. (previously withdrawn) The method recited in claim 12 wherein the circuit element comprises a resonator.
18. (previously withdrawn) The method recited in claim 12 wherein the caulking agent caulked at least a portion of the cap.
19. (previously withdrawn) The method recited in claim 12 wherein the cap includes a gasket that is caulked by the caulking agent.
20. (new) The apparatus recited in claim 1 wherein the caulking agent surrounds said bonding agent at both surfaces of the gasket.
21. (new) The apparatus recited in claim 1 wherein the caulking agent extends from said cap to said device chip.
22. (new) The apparatus recited in claim 1 wherein the caulking agent is adjacent to said bonding agent.

23. (new) The apparatus recited in claim 1 wherein the caulking agent is separated from said bonding agent by open space.

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